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# 1-Mbit (64 K × 16) Static RAM

#### **Features**

■ Temperature Range
□ Automotive: –40 °C to 125 °C

■ High speed

□ t<sub>AA</sub> = 15 ns

■ Optimized voltage range: 2.5 V to 2.7 V

■ Low active power: 220 mW (Max)

■ Automatic power-down when deselected

■ Independent control of upper and lower bits

■ CMOS for optimum speed/power

 Available in Pb-free and non Pb-free 44-pin TSOP II, 44-pin (400-Mil) Molded SOJ and Pb-free 48-ball FPBGA packages

### **Functional Description**

The CY7C1021CV26 is a high-performance CMOS static RAM organized as 65,536 words by 16 bits. This device has

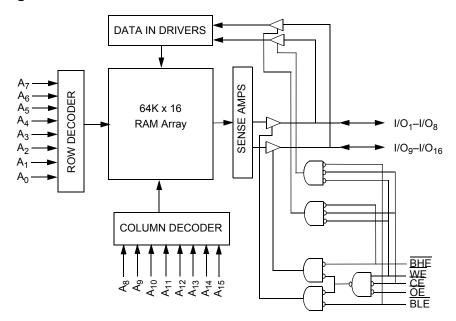
an automatic power-down feature that significantly reduces power consumption when deselected.

Writing to the device is accomplished by taking Chip Enable ( $\overline{\text{CE}}$ ) and Write Enable (WE) inputs LOW. If Byte Low Enable (BLE) is LOW, then data from I/O pins (I/O $_1$  through I/O $_8$ ), is written into the location specified on the address pins (A $_0$  through A $_{15}$ ). If Byte High Enable (BHE) is LOW, then data from I/O pins (I/O $_9$  through I/O $_{16}$ ) is written into the location specified on the address pins (A $_0$  through A $_{15}$ ).

Reading from the device is accomplished by taking Chip Enable ( $\overline{\text{CE}}$ ) and Output Enable ( $\overline{\text{OE}}$ ) LOW while forcing the Write Enable ( $\overline{\text{WE}}$ ) HIGH. If Byte Low Enable ( $\overline{\text{BLE}}$ ) is LOW, then data from the memory location specified by the address pins will appear on I/O<sub>1</sub> to I/O<sub>8</sub>. If Byte High Enable ( $\overline{\text{BHE}}$ ) is LOW, then data from memory will appear on I/O<sub>9</sub> to I/O<sub>16</sub>. See the truth table at the end of this data sheet for a complete description of Read and Write modes.

The input/output pins (I/O $_1$  through I/O $_1$ 6) are placed in a high-impedance state when the device is deselected (CE HIGH), the outputs are disabled (OE HIGH), the BHE and BLE are disabled (BHE, BLE HIGH), or during a Write operation (CE LOW, and WE LOW).

## **Logic Block Diagram**



## CY7C1021CV26



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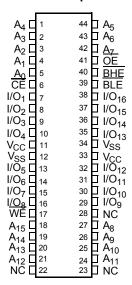


### Selection Guide[1]

	<b>–15</b>	Unit
Maximum Access Time	15	ns
Maximum Operating Current	80	mA
Maximum CMOS Standby Current	10	mA

## Pin Configuration<sup>[2]</sup>

#### **TSOP II -Top View**



#### **Pin Definitions**

Pin Name	Pin Number	I/O Type	Description		
A <sub>0</sub> -A <sub>15</sub>	1–5, 18–21, 24–27, 42–44	Input	Address Inputs used to select one of the address locations.		
I/O <sub>1</sub> –I/O <sub>16</sub>	7–10, 13–16, 29–32, 35–38	Input/Output	Bidirectional Data I/O lines. Used as input or output lines depending on operation		
NC	22, 23, 28	No Connect	No Connects. This pin is not connected to the die.		
WE	17	Input/Control	Write Enable Input, active LOW. When selected LOW, a Write is conducted. When selected HIGH, a Read is conducted.		
CE	6	Input/Control	Chip Enable Input, active LOW. When LOW, selects the chip. When HIGH, deselects the chip.		
BHE, BLE	40, 39	Input/Control	Byte Write Select Inputs, active LOW. BHE controls I/O <sub>16</sub> –I/O <sub>9</sub> , BLE controls I/O <sub>8</sub> –I/O <sub>1</sub> .		
ŌĒ	41	Input/Control	Output Enable, active LOW. Controls the direction of the I/O pins. When LOW, the I/O pins are allowed to behave as outputs. When deasserted HIGH, I/O pins are tri-stated, and act as input data pins.		
V <sub>SS</sub>	12, 34	Ground	Ground for the device. Should be connected to ground of the system.		
V <sub>CC</sub>	11, 33	Power Supply	Power Supply inputs to the device.		

- Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at V<sub>CC</sub> = V<sub>CC(typ.)</sub>, T<sub>A</sub> = 25 °C.
   NC pins are not connected on the die.

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## **Maximum Ratings**

Exceeding maximum ratings may shorten the useful life of the device. User guidelines are not tested. Storage temperature ......-65 °C to +150 °C Ambient temperature with Supply voltage on  $\rm V_{CC}$  to relative  $\rm GND^{[3]}.....-0.5~V$  to +4.6  $\rm V$ 

DC input voltage <sup>[3]</sup>	-0.5 V to V <sub>CC</sub> + 0.5 V
Current into outputs (LOW)	20 mA
Static discharge voltage(per MIL-STD-883, method 3015)	> 2001 V
Latch-up current	> 200 mA

## **Operating Range**

Range	Ambient Temperature	<b>V</b> <sub>CC</sub>	
Automotive	–40 °C to +125 °C	2.5 V-2.7 V	

#### **Electrical Characteristics**

Over the Operating Range

Doromotor	Description	Test Conditions		Unit		
Parameter	Description	rest Conditions	Min	Max	Oille	
V <sub>OH</sub>	Output HIGH voltage	V <sub>CC</sub> = Min, I <sub>OH</sub> = -1.0 mA	2.3	-	V	
$V_{OL}$	Output LOW voltage	V <sub>CC</sub> = Min, I <sub>OL</sub> = 1.0 mA	_	0.4	V	
$V_{IH}$	Input HIGH voltage		2.0	V <sub>CC</sub> + 0.3	V	
V <sub>IL</sub>	Input LOW voltage <sup>[3]</sup>		-0.3	0.8	V	
I <sub>IX</sub>	Input leakage current	$GND \le V_I \le V_{CC}$	-3	+3	μΑ	
I <sub>OZ</sub>	Output leakage current	$GND \le V_I \le V_{CC}$ , output disabled	-3	+3	μΑ	
I <sub>CC</sub>	V <sub>CC</sub> operating supply current	$V_{CC}$ = Max, $I_{OUT}$ = 0 mA, f = $f_{MAX}$ = 1/ $t_{RC}$	_	80	mA	
I <sub>SB1</sub>	Automatic CE Power-Down Current —TTL inputs	Max $V_{CC}$ , $\overline{CE} \ge V_{IH}$ , $V_{IN} \ge V_{IH}$ or $V_{IN} \le V_{IL}$ , $f = f_{MAX}$	_	15	mA	
I <sub>SB2</sub>	Automatic CE Power-Down Current —CMOS inputs	$\begin{array}{l} \text{Max V}_{CC}, \overline{CE} \geq \text{V}_{CC} - 0.3 \text{ V}, \text{V}_{IN} \geq \text{V}_{CC} - 0.3 \text{ V}, \\ \text{or V}_{IN} \leq 0.3 \text{ V}, \text{f} = 0 \end{array}$	_	10	mA	

## Capacitance<sup>[4]</sup>

Parameter	Description Test Conditions		Max	Unit
C <sub>IN</sub>	Input capacitance	$T_A = 25 ^{\circ}\text{C}$ , $f = 1 \text{MHz}$ , $V_{CC} = 2.6 \text{V}$	8	pF
C <sub>OUT</sub>	Output capacitance		8	pF

#### Thermal Resistance<sup>[4]</sup>

Parameter Description		Test Conditions	TSOP-II	Unit
$\Theta_{JA}$	Thermal Resistance (Junction to Ambient)	· · · · · · · · · · · · · · · · · · ·	76.92	°C/W
$\Theta_{\sf JC}$	Thermal Resistance (Junction to Case)	four-layer printed circuit board	15.86	°C/W

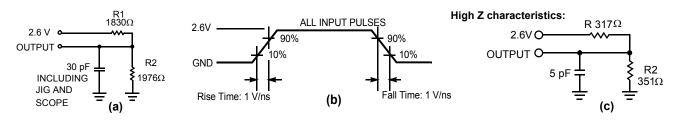
#### Notes

- V<sub>IL</sub> (min.) = -2.0V and V<sub>IH</sub>(max) = V<sub>CC</sub> + 0.5 V for pulse durations of less than 20 ns.
   Tested initially and after any design or process changes that may affect these parameters.

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## AC Test Loads and Waveforms<sup>[5]</sup>



## **Switching Characteristics**

Over the Operating Range<sup>[6]</sup>

Davamatav	Decemention		15	11!4			
Parameter	Description	Min	Max	Unit			
Read Cycle							
t <sub>RC</sub>	Read cycle time	15	_	ns			
t <sub>AA</sub>	Address to data valid	-	15	ns			
t <sub>OHA</sub>	Data hold from address change	3	_	ns			
t <sub>ACE</sub>	CE LOW to data valid	-	15	ns			
t <sub>DOE</sub>	OE LOW to data valid	-	7	ns			
t <sub>LZOE</sub>	OE LOW to low Z <sup>[7]</sup>	0	-	ns			
t <sub>HZOE</sub>	OE HIGH to high Z <sup>[7, 8]</sup>	-	7	ns			
t <sub>LZCE</sub>	CE LOW to low Z <sup>[7]</sup>	3	_	ns			
t <sub>HZCE</sub>	CE HIGH to high Z <sup>[7, 8]</sup>	-	7	ns			
t <sub>PU</sub> <sup>[9]</sup>	CE LOW to power-up	0	_	ns			
t <sub>PD</sub> <sup>[9]</sup>	CE HIGH to power-down	-	15	ns			
t <sub>DBE</sub>	Byte enable to data valid	_	7	ns			
t <sub>LZBE</sub>	Byte enable to low Z	0	-	ns			
t <sub>HZBE</sub>	Byte disable to high Z	-	7	ns			

#### Notes

<sup>5.</sup> AC characteristics (except high Z) are tested using the Thevenin load shown in Figure (a). High Z characteristics are tested for all speeds using the test load shown in Figure (c)

shown in Figure (c)

Test conditions assume signal transition time of 2.6 ns or less, timing reference levels of 1.3 V, input pulse levels of 0 to 2.6 V.

At any given temperature and voltage condition, t<sub>HZCE</sub> is less than t<sub>LZCE</sub>, t<sub>HZOE</sub> is less than t<sub>LZCE</sub>, and t<sub>HZWE</sub> is less than t<sub>LZWE</sub> for any given device.

t<sub>HZOE</sub>, t<sub>HZBE</sub>, t<sub>HZCE</sub>, and t<sub>HZWE</sub> are specified with a load capacitance of 5 pF as in part (d) of AC Test Loads. Transition is measured ±500 mV from steady-state voltage.

This parameter is guaranteed by design and is not tested.



## **Switching Characteristics**

Over the Operating Range<sup>[6]</sup> (continued)

D	Don outoble u	_	15	
Parameter	Description	Min	Max	Unit
Write Cycle <sup>[10]</sup>				•
t <sub>WC</sub>	Write cycle time	15	_	ns
t <sub>SCE</sub>	CE LOW to write end	10	_	ns
t <sub>AW</sub>	Address set-up to write end	10	_	ns
t <sub>HA</sub>	Address hold from write end	0	_	ns
t <sub>SA</sub>	Address set-up to write start	0	_	ns
t <sub>PWE</sub>	WE pulse width	10	_	ns
t <sub>SD</sub>	Data set-up to write end	8	_	ns
t <sub>HD</sub>	Data hold from write end	0	_	ns
t <sub>LZWE</sub>	WE HIGH to low Z <sup>[11]</sup>	3	_	ns
t <sub>HZWE</sub>	WE LOW to high Z <sup>[11, 12]</sup>	-	7	ns
t <sub>BW</sub>	Byte enable to end of write	9	_	ns

Notes

10. The internal Write time of the memory is defined by the overlap of CE LOW, WE LOW and BHE/BLE LOW. CE, WE and BHE/BLE must be LOW to initiate a Write, and the transition of these signals can terminate the Write. The input data set-up and hold timing should be referenced to the leading edge of the signal that terminates the Write.

11. At any given temperature and voltage condition, there is less than the transition of these signals that terminates the Write.

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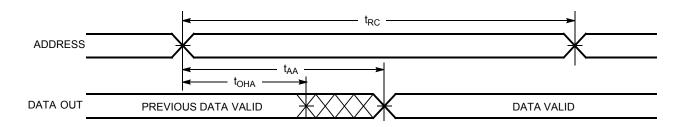
23. the transition of these signals can terminate the Write.

24. the transition of the transition of the transition of

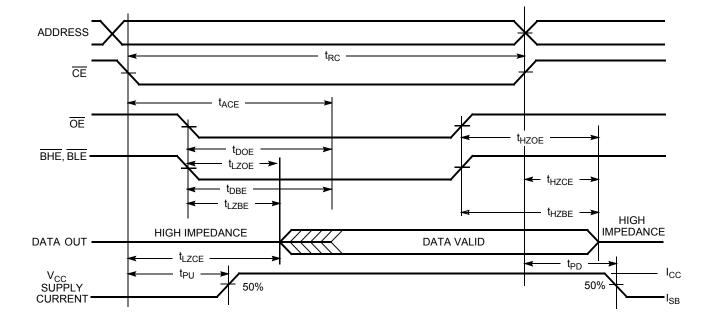


## **Switching Waveforms**

## Read Cycle No. 1<sup>[13, 14]</sup>



# Read Cycle No. 2 (OE Controlled)[14, 15]



- 13. <u>Device</u> is continuously selected. <u>OE</u>, <u>CE</u>, <u>BHE</u> and/or <u>BLE</u> = V<sub>IL</sub>.

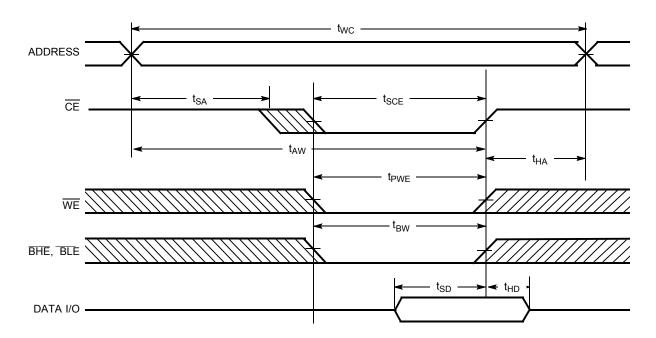
  14. WE is HIGH for Read cycle.

  15. Address valid prior to or coincident with <u>CE</u> transition LOW.

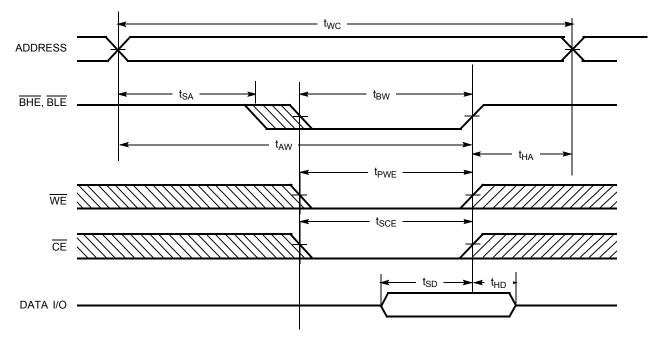


## **Switching Waveforms** (continued)

## Write Cycle No. 1 (CE Controlled)[16, 17]



## Write Cycle No. 2 (BLE or BHE Controlled)



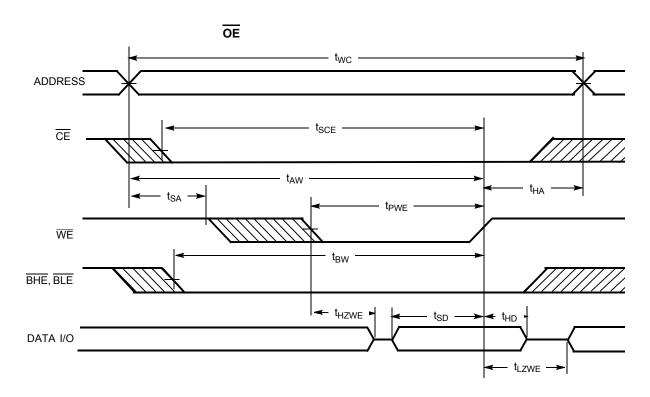
16. Data I/O is high-impedance if OE or BHE and/or BLE= V<sub>IH</sub>.

17. If CE goes HIGH simultaneously with WE going HIGH, the output remains in a high-impedance state.



# **Switching Waveforms** (continued)

Write Cycle No. 3 (WE Controlled, LOW)



## **Truth Table**

CE	OE	WE	BLE	BHE	I/O <sub>1</sub> –I/O <sub>8</sub>	I/O <sub>9</sub> -I/O <sub>16</sub>	Mode	Power
Н	Х	Х	X	Χ	High Z	High Z	Power-down	Standby (I <sub>SB</sub> )
L	L	Н	L	L	Data Out	Data Out	Read – All bits	Active (I <sub>CC</sub> )
			L	Н	Data Out	High Z	Read – Lower bits only	Active (I <sub>CC</sub> )
			Н	L	High Z	Data Out	Read – Upper bits only	Active (I <sub>CC</sub> )
L	Х	L	L	L	Data In	Data In	Write – All bits	Active (I <sub>CC</sub> )
			L	Н	Data In	High Z	Write – Lower bits only	Active (I <sub>CC</sub> )
			Н	L	High Z	Data In	Write – Upper bits only	Active (I <sub>CC</sub> )
L	Н	Н	Х	Х	High Z	High Z	Selected, Outputs Disabled	Active (I <sub>CC</sub> )
L	Х	Х	Н	Н	High Z	High Z	Selected, Outputs Disabled	Active (I <sub>CC</sub> )



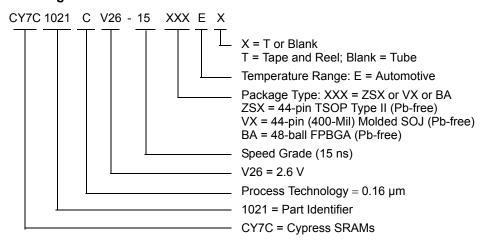
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Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
15	CY7C1021CV26-15ZSXE	51-85087	44-pin TSOP Type II (Pb-free)	Automotive
	CY7C1021CV26-15VXE	51-85082	44-pin (400-Mil) Molded SOJ (Pb-free)	
	CY7C1021CV26-15BAE	51-85150	48-ball FPBGA (6 × 8 × 1 mm) (Pb-free)	
	CY7C1021CV26-15BAET	51-85150	48-ball FPBGA (6 × 8 × 1 mm) (Pb-free)	
	CY7C1021CV26-15VXET	51-85082	44-pin (400-Mil) Molded SOJ (Pb-free)	
	CY7C1021CV26-15ZSXET	51-85087	44-pin TSOP Type II (Pb-free)	

#### **Ordering Code Definitions**





## **Package Diagrams**

Figure 1. 44-pin TSOP II, 51-85087

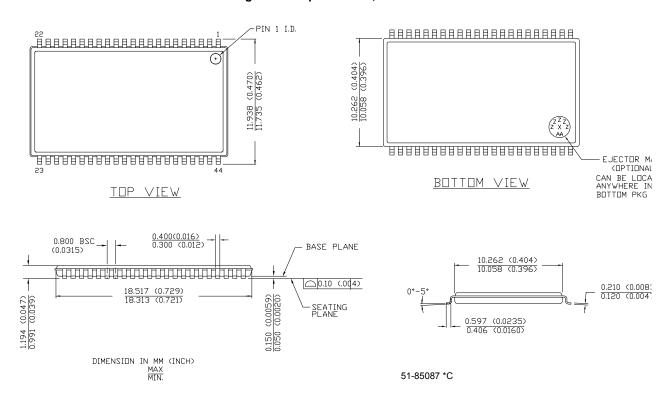
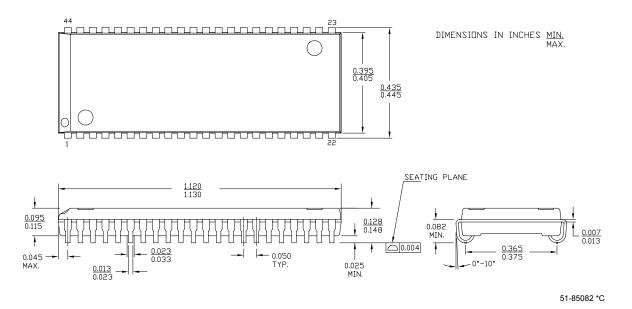


Figure 2. 44-pin (400-Mil) Molded SOJ, 51-85082

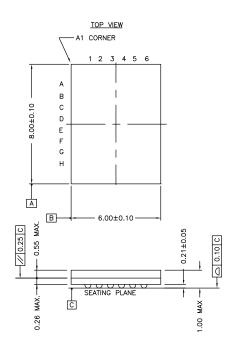


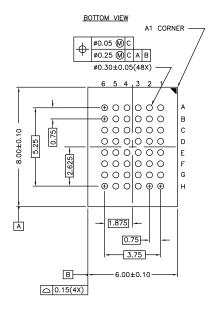
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# Package Diagrams (continued)

Figure 3. 48-ball FBGA (6 × 8 × 1 mm), 51-85150





51-85150 \*F



## **Acronyms**

Acronym	Description	
CMOS	complementary metal oxide semiconductor	
CE	chip enable	
I/O	input/output	
OE	output enable	
SOJ	small outline J-lead	
SRAM	static random access memory	
TSOP	thin small-outline package	
TTL	transistor-transistor logic	
FPBGA	fine-pitch ball grid array	
WE	write enable	

## **Document Conventions**

### **Units of Measure**

Symbol	Unit of Measure			
ns	nano seconds			
V	Volts			
μΑ	micro Amperes			
mA	milli Amperes			
mW	milli Watts			
MHz	Mega Hertz			
pF	pico Farad			
°C	degree Celcius			
W	Watts			
%	percent			



# **Document History Page**

ocument Title: CY7C1021CV26 1-Mbit (64 K × 16) Static RAM ocument Number: 38-05589						
REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change		
**	238454	See ECN	RKF	New data sheet for Automotive		
*A	335861	See ECN	SYT	Added Lead-Free Product Information Included the 44-Lead (400-Mil) Molded SOJ V34 Package		
*B	493543	See ECN	NXR	Changed the description of I <sub>IX</sub> from Input Load Current to Input Leakage Current in DC Electrical Characteristics table Removed I <sub>OS</sub> parameter from DC Electrical Characteristics table Updated Ordering Information Table		
*C	2897087	03/22/10	AJU	Removed obsolete parts from ordering information table Updated package diagrams		
*D	3057593	10/13/2010	PRAS	Updated Ordering Information and added Ordering Code Definition: Updated Package Diagrams.		
*E	3098812	12/01/2010	PRAS	Added Acronyms and Units of Measure. Minor edits and updated in new template.		

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